

RoHS Compliant HF

REV.	ECN.NO.	MODIFY.CONTENT
X1	2023-03-14	NEW

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY,GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS,80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 0.5A;
- 2.2 VOLTAGE RATING: 50V.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 500MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3.ORDER INFORMATION:

FB01-080FXXX0834XX

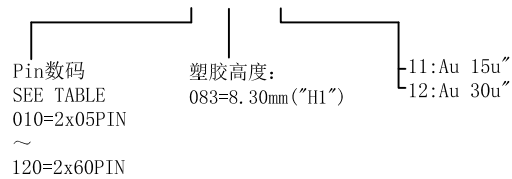
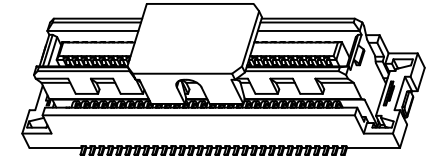
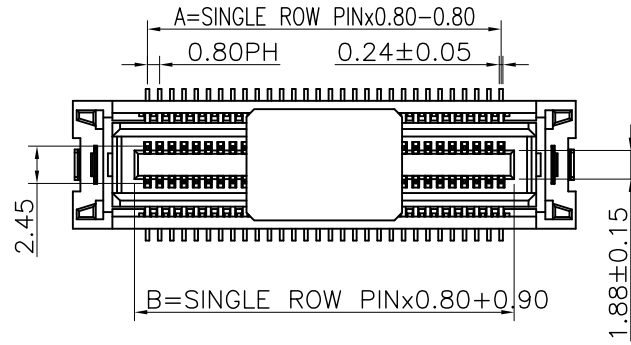
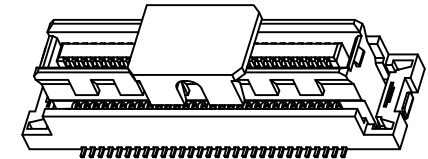


TABLE 1:

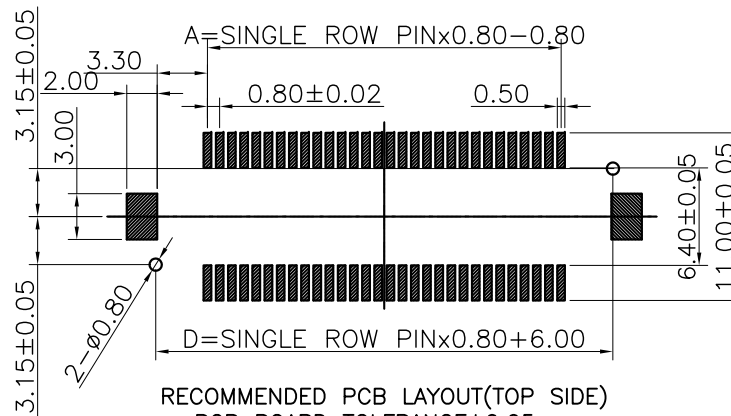
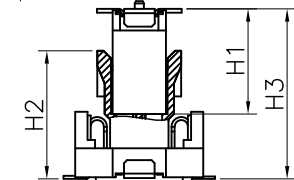
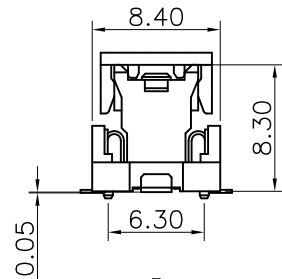
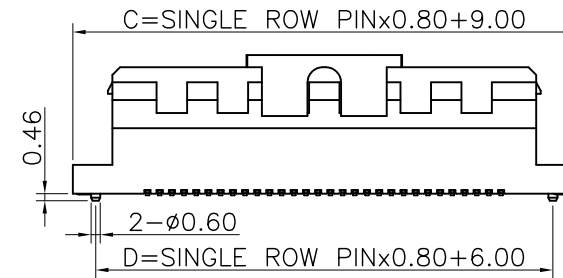
No. OF PIN	A	B	C	D
010=2x05PIN	3.20	4.90	13.00	10.00
020=2x10PIN	7.20	8.90	17.00	14.00
030=2x15PIN	11.20	12.90	21.00	18.00
040=2x20PIN	15.20	16.90	24.00	22.00
050=2x25PIN	19.20	20.90	29.00	26.00
060=2x30PIN	23.20	24.90	33.00	30.00
080=2x40PIN	31.20	32.90	41.00	38.00
100=2x50PIN	39.20	40.90	49.00	46.00
120=2x60PIN	43.20	44.90	53.00	50.00



2*40PIN ~ 2*60PIN 无槽



2*5PIN ~ 2*30PIN 无槽



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT

MATING HEIGHT	H1	H2	H3
11.75mm	4.80	4.90	6.00
12.75mm	6.80		8.00
MATING HEIGHT	7.80	8.30	9.00
11.75mm	4.80		11.75
12.75mm	6.80		12.75
12.75mm	7.80		12.75

GENERAL TOLERANCE	DWG.NO.	F B01-080FXXX083400	PART.NO.	F B01-080FXXX0834XX	DRAWN	Brian 2023-03-14
x.±0.50	REV.	X1	TITLE	浮动板对板0.8Pitch母座直立式	CHECKED	
.x±0.25	SIZE	A4	SHEET	1 OF 1	APPROVED	
.xx±1°						

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